

AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior versions, and all prior listings, of claims in the application.

Listing of Claims:

Claims 1.-13. (Cancelled)

14. (Withdrawn) A method of producing a substrate for mounting semiconductor devices thereon, said substrate having an insulating supporting member and plural sets of wiring, comprising the steps of:

forming plural sets of a semiconductor device mounting region and a resin-sealing semiconductor package region outside of said semiconductor device mounting region on a surface of said insulating supporting member;

forming said plural sets of wiring with a predetermined wiring pattern including wire-bonding terminals, external connecting terminals and the wirings that connect said wire-bonding terminals with said external connecting terminals,

wherein in the wiring forming step, said wiring is formed in a manner that said semiconductor device mounting region and said semiconductor packaging region are arranged repeatedly in plural numbers in a row and a column respectively with the same predetermined wiring pattern.

15. (Withdrawn) The method of producing a substrate for mounting semiconductor devices thereon according to claim 14, wherein in said step of forming said plural sets of wiring; there are provided plural number of blocks of said wiring formed in a manner that said semiconductor device mounting region and said

semiconductor packaging region are arranged repeatedly in plural numbers in a row and a column respectively with the same predetermined wiring pattern.

16. (Withdrawn) The method of producing a substrate for mounting semiconductor devices thereon according to claim 14, wherein said wire-bonding terminal is formed in said semiconductor package region and said method further comprises the step of plating nickel and gold on a surface of said wire-bonding terminal.

17. (Withdrawn) The method of producing a substrate for mounting semiconductor devices thereon according to claim 14, wherein said external connecting terminals are exposed on a surface of said insulating supporting member, on an opposite side of which said semiconductor device is mounted, and are arranged in a grid pattern at positions corresponding to said semiconductor device mounting region and said semiconductor packaging region.

18. (Withdrawn) The method of producing a substrate for mounting semiconductor devices thereon according to claim 14, wherein said wiring is formed on one surface of said insulating supporting member, and said method further comprising the step of forming openings in said external connecting terminals in said insulating support member.

19. (Withdrawn) The method of producing a substrate for mounting semiconductor devices thereon according to claim 18, wherein said openings are

formed at least by any of stamping, drilling, laser beam matching and wet etching.

20. (Withdrawn) The method of producing a substrate for mounting semiconductor devices thereon according to claim 14, wherein said insulating supporting member comprises an adhesive layer on its surface, said method further comprises, after the step of forming said openings, the steps of bonding said insulating supporting member and a piece of metallic foil via said adhesive layer, and in the step of forming said plural sets of wiring, said wiring is formed by etching said piece of metallic foil thus bonded.

21. (Withdrawn) The method of producing a substrate for mounting semiconductor devices thereon according to claim 14, wherein said insulating supporting member comprises a piece of metallic foil on its surface and wherein in the step of forming said plural sets of wiring, said wiring is formed by etching said piece of metallic foil.

22.-23. (Cancelled)

24. (Currently Amended) The substrate for mounting semiconductor devices thereon according to claim ~~22~~ 32, wherein ~~said wire-bonding terminal is formed in said semiconductor packaging region, and~~ said wire-bonding terminals ~~comprises~~ comprise a nickel layer and gold plate layer on its surface.

25. (Currently Amended) The substrate for mounting semiconductor devices thereon according to claim 22 32, wherein said external connecting terminals are exposed on a surface of said insulating supporting member, on opposite side of which said semiconductor device is mounted, and are arranged in a grid pattern at positions corresponding to said semiconductor device mounting region and said semiconductor packaging region.

26. (Cancelled)

27. (Withdrawn) The method of producing a semiconductor package comprising the steps of:

mounting a semiconductor device on each of said plural semiconductor devices mounting regions of the substrate for mounting semiconductor device thereon according to claim 22 by employing a die bonding material;

electrically connecting said semiconductor device with said wire-bonding terminal by wire-bonding;

sealing said semiconductor package region including said plural semiconductor devices with a sealing resin connected in one-piece;

forming solder bumps on said external connection terminals; and cutting said substrate for mounting semiconductor devices thereon and said

sealing resin in one operation to be separated into the individual semiconductor package.

28. (Withdrawn) The method of producing a semiconductor package according to claim 27, wherein said die-bonding material is a die-bonding film.

29. (Withdrawn) The method of producing a semiconductor package according to claim 27, wherein said die-bonding material is a die-bonding tape.

30. (Withdrawn) The method of producing a semiconductor package according to claim 27, wherein said cutting is carried out by dicing work.

31. (Currently Amended) The semiconductor package produced by a method comprising the steps of:

mounting a semiconductor device on each of said plural semiconductor devices mounting regions of the substrate for mounting semiconductor device thereon according to claim ~~22~~ 32 by employing a die bonding material;

electrically connecting said semiconductor device with said wire-bonding terminal by wire-bonding;

sealing said semiconductor package region including said plural semiconductor devices with a sealing resin connected in one-piece;

forming solder bumps on said external connection terminals; and

cutting said substrate for mounting semiconductor devices thereon and said sealing resin in one operation to be separated into the individual semiconductor package.

32. (New) A substrate for mounting semiconductor devices thereon having an insulating supporting member and plural sets of wirings, and further comprising:

- a semiconductor device mounting region and a resin-sealing semiconductor package region outside of said semiconductor device mounting region,
- wherein said plural sets of wirings comprise a predetermined wiring pattern including wire-bonding terminals and external connection terminals,
- wherein said wire bonding terminals are provided in said semiconductor package region and said external connection terminals are provided in said semiconductor device mounting region,
- wherein said substrate includes a plurality of said semiconductor device mounting regions, and
- wherein said plurality of said semiconductor device mounting regions respectively have blocks of said wirings, each having a same pattern.

33. (New) A substrate for mounting semiconductor devices thereon, having an insulating supporting member and plural sets of wirings,

- wherein:
- said wirings form a predetermined wiring pattern including a wire bonding terminal and an external connection terminal; and
- said external connection terminal is provided only inside of said wire bonding terminal.

34. (New) The substrate for mounting semiconductor device thereon according to claim 33, comprising a plurality of said wiring patterns comprised of a

plurality of said wirings arranged in rows and columns.

35. (New) The substrate for mounting semiconductor devices thereon according to claim 33, wherein said wire-bonding terminal comprises a nickel layer and a gold plate layer on its surface.

36. (New) The substrate for mounting semiconductor devices thereon according to claim 33,
wherein said external connection terminal is one of a plurality of external connection terminals, exposed on a surface of said insulating supporting member, on an opposite side to which said semiconductor device is mounted, and said external connection terminals are arranged in a grid patterns at positions corresponding to a semiconductor device mounting region and a semiconductor package region of said substrate.

37. (New) A semiconductor package produced by a method comprising the steps of:

mounting a semiconductor device on each of said plural semiconductor device mounting regions of the substrate for mounting the semiconductor device thereon according to claim 33 by employing a die-bonding material,

electrically connecting the semiconductor device with the wire-bonding terminals by wire-bonding,

sealing said semiconductor package region including said semiconductor device with a sealing resin connected in one-piece;

forming solder bumps on said external connection terminals; and
cutting said substrate for mounting the semiconductor device thereon and
said sealing resin in one operation to be separated into the individual semiconductor
package.